

PNC's Technology Roadmap

PNC's technology road map is a guide to enable us to schedule planned improvement in our current capabilities to serve our customer better. It also helps us to fulfill our commitment to ISO9001:2000 requirement of continuous improvement to achieve measurable customer satisfaction.

Following table shows our current capability as of April 1, 2007 and also our plan for years 2008 and 2009.

No.	Manufacturing Capabilities	2007	2008	2009
1	Drilling Aspect Ratio	6:1	9:1	15:1
2	Minimum Drill Size	.010	.008	.006
3	Minimum Inner Layer Pad Size	.018	.016	.014
4	Minimum Outer Layer Pad Size	.018	.016	.014
5	Minimum Anti-Pad on Power/Ground Planes	.018	.016	.014
6	Minimum Buried/Blind Via Pad Size	.018	.016	.014
7	Minimum Buried/Blind Via Hole Size	.010	.008	.006
8	Minimum Inner Layer Line Width	.003	.003	.003
9	Minimum Outer Layer Line Width	.003	.003	.003
10	Minimum Inner Layer Spacing	.003	.003	.003
11	Minimum Outer Layer Spacing	.003	.003	.003
12	Maximum Overall Board Thickness	.250	.250	.250
13	Minimum Dielectric Thickness	.003	.0025	.002
14	Minimum Component Pitch-Plating and Testing	.012	.010	.008
15	Layer to Layer Registration Tolerance	.004	.004	.003
16	Conductor to Board Edge	.010	.008	.005
17	Solder Mask Clearance	.004	.003	.002
18	Solder Mask Dam between SMT Pads	.003	.003	.002
19	Minimum Base Copper Weight in oz.	.5	.5	.25
20	Maximum Overall Copper thickness	5	6	8
21	Maximum Layer Count	18	24	30
22	Plated Hole Tolerance	±.003	±.002	±.002
23	Maximum PCB Dimensions	19x25	19x25	19x25
24	Impedance Tolerance	±8%	±7.5%	±5%
25	Materials Available	Current: Multifunctional FR-4, High Tg FR-4, Polyimide, Rogers, Duroid, Teflon, ISOLA 370HR(Tg 180 Degree C)		

No.	Manufacturing Capabilities	2007	2008	2009
		Future: Other materials will be added as required		
26	Surface Finish Available	HASL, Tin/Lead, Nickel/Gold, OSP, Selective or hard or full body gold, Immersion Tin, Nickel and Gold & silver		
27	Equipments Purchase Plan	Laser Drill – Year 2006 Direct Imaging – Year 2007 Post Etch Punch – Year 2006 Film Punch - Year 2006 Plasma Etch System - Year 2006 Direct Image Silk Screen - Year 2006		
28	CAD/CAM Formats	<u>2007</u> DXF,HPGL, Gerber, PDF, Auto CAD,274X.IPC- D350,Orbotech, ECAM dsn,	<u>2009</u> Valor Genesis ODB ++	

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